

**N - CHANNEL ENHANCEMENT MODE
POWER MOS TRANSISTOR**

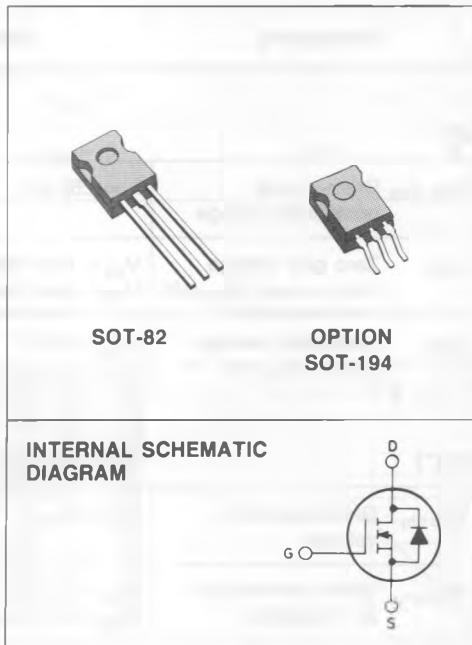
TYPE	V _{DSS}	R _{DS(on)}	I _D
SGSP222	50 V	0.13 Ω	10 A

- HIGH SPEED SWITCHING APPLICATIONS
- ULTRA FAST SWITCHING
- EASY DRIVE FOR REDUCED COST AND SIZE

INDUSTRIAL APPLICATIONS:

- SWITCHING POWER SUPPLIES
- MOTOR CONTROLS.

N - channel enhancement mode POWER MOS field effect transistor. Easy drive and very fast switching times make this POWER MOS transistor ideal for high speed switching applications. Uses include general motor speed control, low voltage DC/DC converters and solenoid driving.


**INTERNAL SCHEMATIC
DIAGRAM**

ABSOLUTE MAXIMUM RATINGS

V _{DS}	Drain-source voltage (V _{GS} = 0)	50	V
V _{DGR}	Drain-gate voltage (R _{GS} = 20 kΩ)	50	V
V _{GS}	Gate-source voltage	±20	V
I _D	Drain current (cont.) at T _c = 25°C	10	A
I _D	Drain current (cont.) at T _c = 100°C	6.3	A
I _{DM (*)}	Drain current (pulsed)	40	A
I _{DLM (*)}	Drain inductive current, clamped	40	A
P _{tot}	Total dissipation at T _c < 25°C	50	W
	Derating factor	0.4	W/°C
T _{stg}	Storage temperature	-65 to 150	°C
T _J	Max. operating junction temperature	150	°C

(*) Pulse width limited by safe operating area

THERMAL DATA

$R_{thj \text{- case}}$	Thermal resistance junction-case	max	2.5	$^{\circ}\text{C}/\text{W}$
T_L	Maximum lead temperature for soldering purpose		275	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_{case} = 25^{\circ}\text{C}$ unless otherwise specified)

Parameters	Test Conditions	Min.	Typ.	Max.	Unit
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OFF

$V_{(BR) DSS}$	Drain-source breakdown voltage	$I_D = 250 \mu\text{A}$	$V_{GS} = 0$	50			V
I_{DSS}	Zero gate voltage drain current ($V_{GS} = 0$)	$V_{DS} = \text{Max Rating}$	$V_{DS} = \text{Max Rating} \times 0.8$	$T_c = 125^{\circ}\text{C}$		250 1000	μA μA
I_{GSS}	Gate-body leakage current ($V_{DS} = 0$)	$V_{GS} = \pm 20 \text{ V}$				± 100	nA

ON (*)

$V_{GS \text{ (th)}}$	Gate threshold voltage	$V_{DS} = V_{GS}$	$I_D = 250 \mu\text{A}$	2		4	V
$R_{DS \text{ (on)}}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}$	$I_D = 5 \text{ A}$	$V_{GS} = 10 \text{ V}$	$I_D = 5 \text{ A}$	$T_c = 100^{\circ}\text{C}$	0.13 0.26

DYNAMIC

g_s	Forward transconductance	$V_{DS} = 25 \text{ V}$	$I_D = 5 \text{ A}$	3			mho
C_{iss} C_{oss} C_{rss}	Input capacitance Output capacitance Reverse transfer capacitance	$V_{DS} = 25 \text{ V}$ $V_{GS} = 0$	$f = 1 \text{ MHz}$		460	550 350 180	pF pF pF

SWITCHING

$t_d \text{ (on)}$	Turn-on time	$V_{DD} = 25 \text{ V}$	$I_D = 5 \text{ A}$	15	20	ns
t_r	Rise time	$V_i = 10 \text{ V}$	$R_i = 4.7 \Omega$	40	55	ns
$t_d \text{ (off)}$	Turn-off delay time	(see test circuit)		40	55	ns
t_f	Fall time			20	30	ns

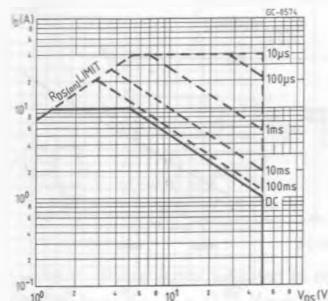
ELECTRICAL CHARACTERISTICS (Continued)

Parameters	Test Conditions		Min.	Typ.	Max.	Unit
I_{SD}					10	A
$I_{SDM} (\text{puls})$	Source-drain current (pulsed)			40		A
V_{SD}	Forward on voltage	$I_{SD} = 10 \text{ A}$	$V_{GS} = 0$		1.4	V
t_{rr}	Reverse recovery time	$I_{SD} = 10 \text{ A}$	$V_{GS} = 0$	100		ns
dI/dt		$dI/dt = 25 \text{ A}/\mu\text{s}$				

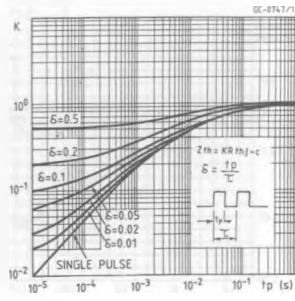
(P) Pulsed: Pulse duration = 300 μs , duty cycle 1.5%

(R) Pulse width limited by safe operating area

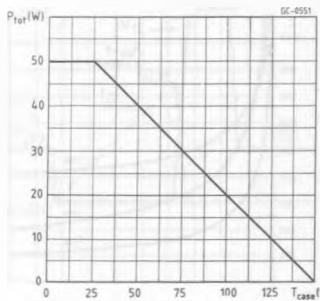
Safe operating areas



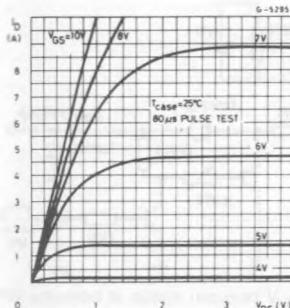
Thermal impedance



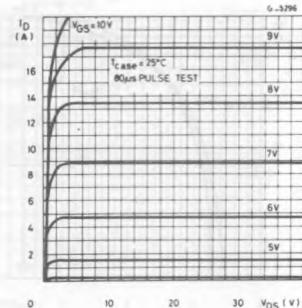
Derating curve



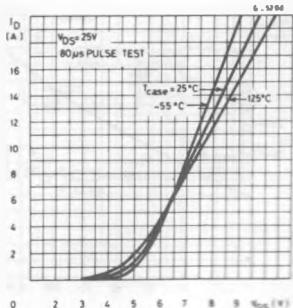
Output characteristics



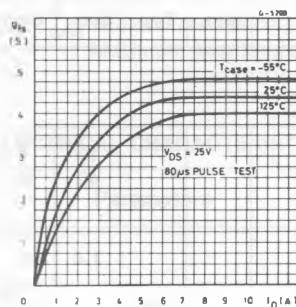
Output characteristics



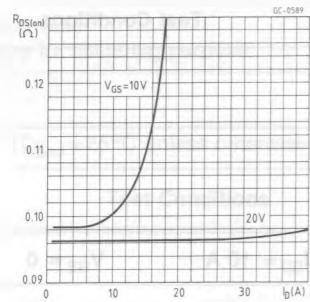
Transfer characteristics



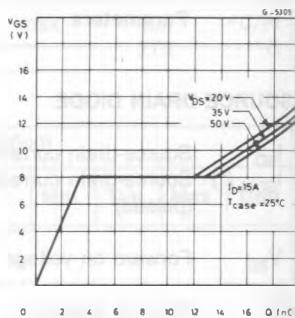
Transconductance



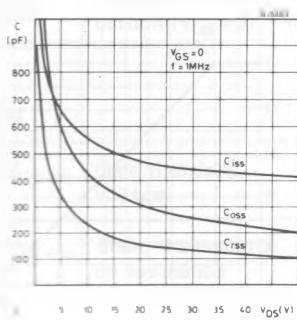
Static drain-source on resistance



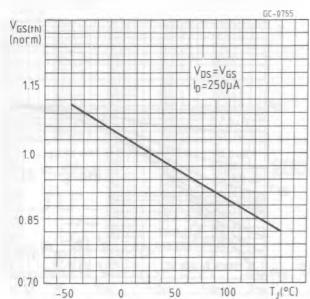
Gate charge vs gate-source voltage



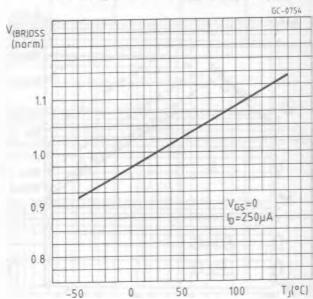
Capacitance variation



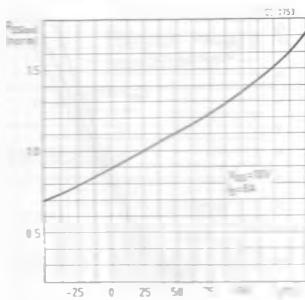
Normalized gate threshold voltage vs temperature



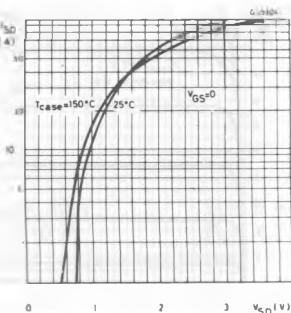
Normalized breakdown voltage vs temperature



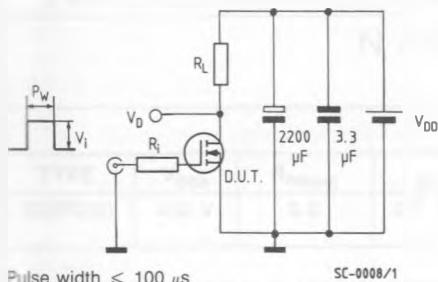
Normalized on resistance vs temperature



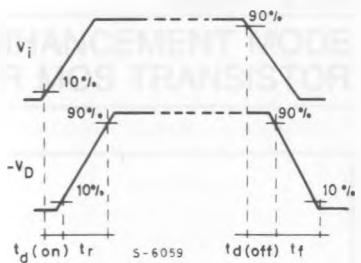
Source-drain diode forward characteristics



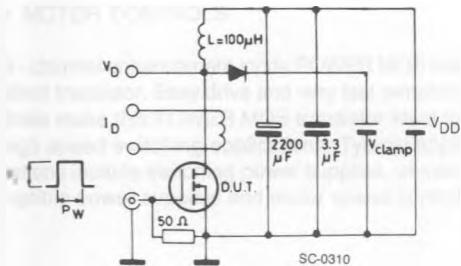
Switching times test circuit for resistive load



Switching time waveforms for resistive load

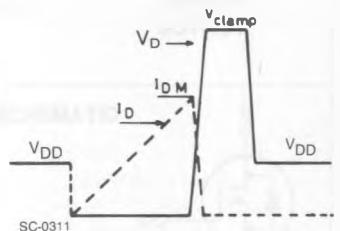


Clamped inductive load test circuit

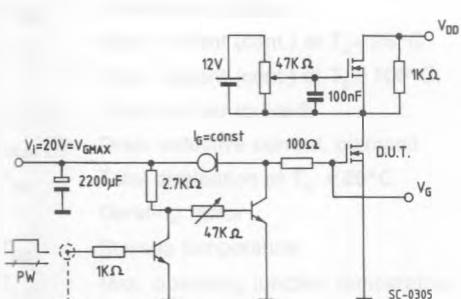


$V_i = 12 \text{ V}$ - Pulse width: adjusted to obtain specified I_{DM} , $V_{clamp} = 0.75 V_{(BR) DSS}$.

Clamped inductive waveforms



Gate charge test circuit



PW adjusted to obtain required V_G

Body-drain diode t_{rr} measurement
Jedec test circuit